




SPECIFICATION SHEET

SPECIFICATION SHEET NO.	N0310- SOT23T5401S02L
DATE	Mar. 10, 2021
REVISION	A0
DESCRIPTION	<p>SMD Plastic-Encapsulate Transistors, SOT-23 series, 3 pads</p> <p>MMBT5401 Type, Complementary PNP</p> <p>Collector Power Dissipation 300mW. Collector Current 600mA Max.</p> <p>Operating Temp. Range -55°C ~+150°C,</p> <p>Package in Tape/Reel, 3000pcs/Reel</p> <p>RoHS/RoHS III compliant</p>
CUSTOMER	
CUSTOMER PART NUMBER	
CROSS REF. PART NUMBER	
ORIGINAL PART NUMBER	MDD MMBT5401
PART CODE	SOT23T5401S02L

VENDOR APPROVE		
Issued/Checked/Approved		
		
DATE: March 10, 2021		

CUSTOMER APPROVE
DATE:

SMD PLASTIC-ENCAPULATE TRANSISTORS SOT23 SERIES

MAIN FEATURE

- Epitaxial planar die construction
- Complementary PNP
- Collector Power Dissipation 300mW
- Collector Current 600mA.



APPLICATION

- For printed circuit board

RFQ

[Request For Quotation](#)

PART CODE GUIDE

SOT23	T5401	S	02L
1	2	3	4

- 1) **SOT23**: SMD Plastic-Encapsulate Transistors, 3 pads SOT-23 series Code
- 2) **T5401**: Type code for MMBT5401
- 3) **S**: Package code, Package in Tape/Reel, 3000pcs/Reel
- 4) **02L**: Marking code for “2L” on the case surface, Different Marking for different specification.

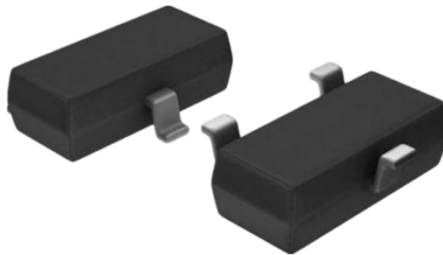
MORE ITEMS AVAILABLE

SOT23C1623S0L4	SOT23C1623S0L5	SOT23C1623S0L6	SOT23C1623S0L7	SOT23C3356SR23
SOT23C3356SR24	SOT23C3356SR25	SOT23T493AS93A	SOT23BC807SAW	SOT23BC807SBW
SOT23BC807SCW	SOT23BC856S03A	SOT23BC856S03B	SOT23BC857S03E	SOT23BC857S03F
SOT23BC857S03G	SOT23BC858S03J	SOT23BC858S03K	SOT23BC858S03L	SOT23T5401S02L
SOT2355551S0G1	SOT23BTA44S03D	SOT23BTA94S04D	SOT23BTA56S2GM	SOT232222AS01P
SOT232907AS02F	SOT23T3904S1AM	SOT23T3906S02A	SOT23T4401S02X	SOT23T4403S02T
SOT23S8050SJ3Y	SOT23S8550S2TY	SOT23S9012S2T1	SOT23S9013S0J3	SOT23S9014S0J6
SOT23S9015S0M6	SOT23S9018S0J8	SOT23SS805S0Y1	SOT23SS855S0Y2	
SOT23BC817S06A	SOT23BC817S06B	SOT23BC817S06C		

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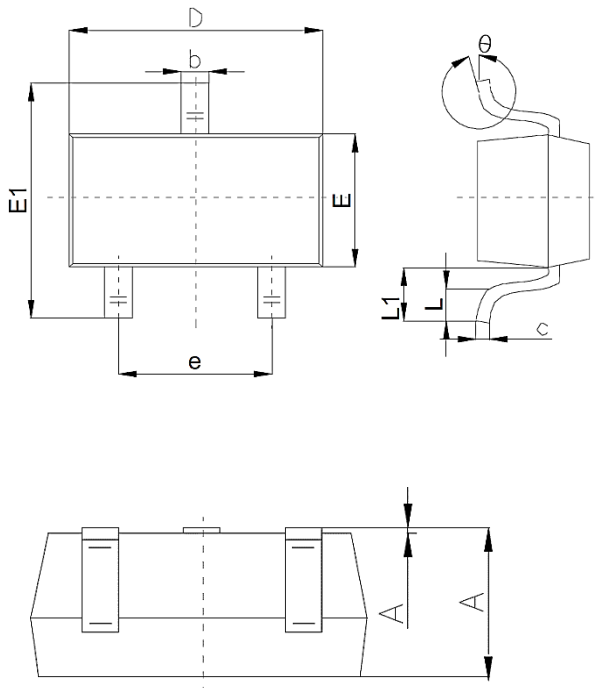
DIMENSION (Unit: Inch/mm)

Image for reference



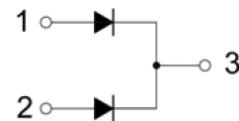
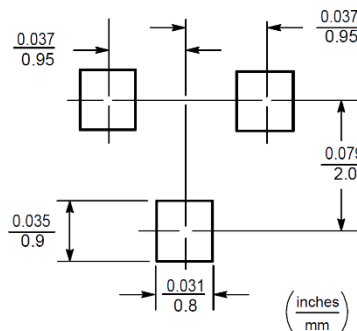
Marking: 2L

SOT-23



Symbol	Value (mm)		
	Min.	Typ.	Max.
A	1.0		1.4
A1			0.10
b	0.35		0.50
c	0.10		0.20
D	2.70	2.90	3.10
E	1.40		1.60
E1	2.40		2.80
e		1.9	
L	0.10		0.30
L1	0.40		
θ	0°		10°

Recommend Pad Layout



- 1.Base
- 2.Emitter
- 3.Collector

SMD PLASTIC-ENCAPULATE TRANSISTORS SOT23 SERIES
MECHANICAL DATA

Case	Terminals	Polarity	Mounting Position	Weight per piece
JEDEC SOT-23 molded plastic body	Solder plated, Solderable per MIL-STD-750, Method 2026	Polarity symbol marking on case	Any	0.00019 Ounce, 0.00591 grams

MAX. RATINGS AT Ta=25 °C

Parameter	SYMBOLS	VALUE	UNITS
		LIMIT	
Collector-Base Voltage	V _{CBO}	-160	Volts
Collector-Emitter Voltage	V _{CEO}	-160	Volts
Emitter-Base Voltage	V _{EBO}	-5	Volts
Collector Current	I _C	-0.6	A
Collector Power Dissipation	P _C	0.3	W
Thermal Resistance Junction to Ambient	R _{QJA}	416	°C/W
Junction temperature	T _J	+150	°C
Storage temperature range	T _{STG}	-55 ~ +150	°C

SMD PLASTIC-ENCCAPULATE TRANSISTORS SOT23 SERIES
ELECTRICAL CHARACTERISTICS AT Ta= 25 °C

Parameter	SYMBOLS	VALUE			UNIT	Condition
		Min.	Typ.	Max.		
Collector-base breakdown voltage	$V_{(BR)CBO}$	-160			V	$I_C = -100\mu A, I_E = 0$
Collector-emitter breakdown voltage	$V_{(BR)CEO}^*$	-150			V	$I_C = -1mA, I_B = 0$
Emitter-base breakdown voltage	$V_{(BR)EBO}$	-5			V	$I_E = -10\mu A, I_C = 0$
Collector cut-off current	I_{CBO}			-0.1	μA	$V_{CB} = -120V, I_E = 0$
Emitter cut-off current	I_{EBO}			-0.1	μA	$V_{EB} = -4V, I_C = 0$
DC Current gain	$h_{FE(1)}^*$	80				$V_{CE} = -5V, I_C = -1mA$
	$h_{FE(2)}$	100		300		$V_{CE} = -5V, I_C = -10mA$
	$h_{FE(3)}^*$	50				$V_{CE} = -5V, I_C = -50mA$
Collector-emitter saturation voltage	$V_{CE(sat)}^*$			-0.2	V	$I_C = -10mA, I_B = -1mA$ $I_C = -50mA, I_B = -5mA$
				-0.5		
Base-emitter saturation voltage	$V_{BE(sat)}^*$			-1	V	$I_C = -10mA, I_B = -1mA$ $I_C = -50mA, I_B = -5mA$
				-1		
Transition frequency	f_T	100			MHz	$V_{CE} = -5V, I_C = -10mA, f = 30MHz$
Delay time	t_d			-	ns	-
Rise time	t_r			-	ns	-
Storage time	t_s			-	ns	-
Fall time	t_f			-	ns	-

Note: * pulse test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2.0\%$.

CLASSIFICATION OF h_{FE}

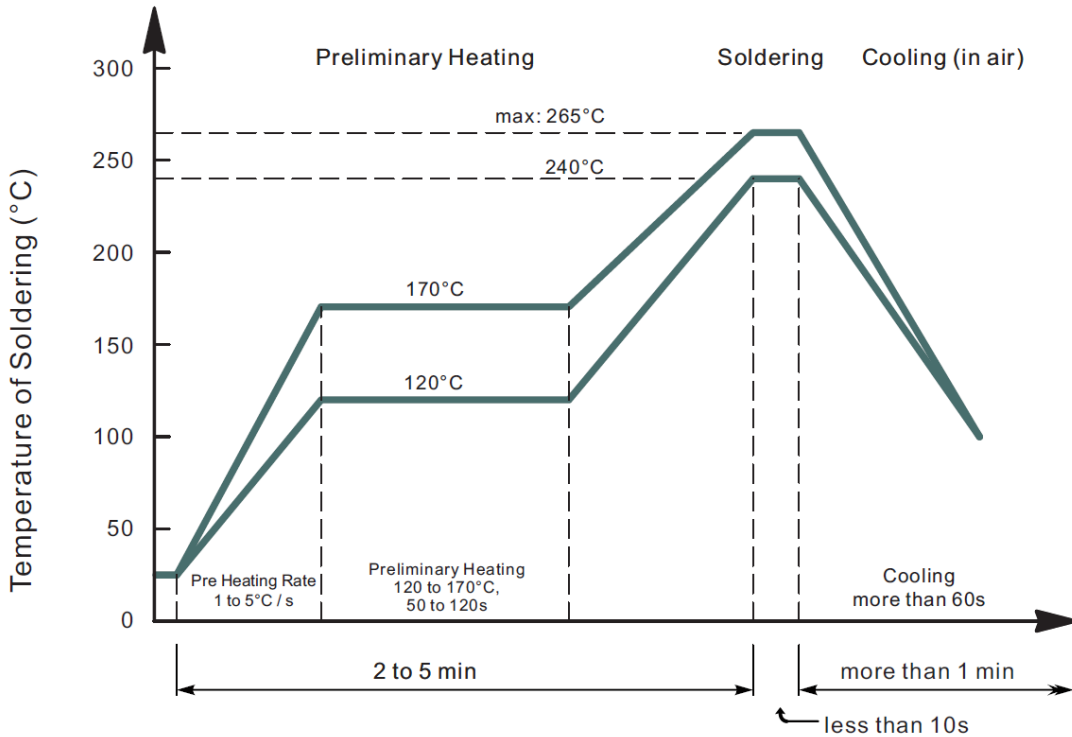
Rank	L	H
Range	100 ~ 200	200 ~ 300
Marking	2L	2L

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RELIABILITY

Number	Experiment Items	Experiment Method And Conditions	Reference Documents
1	Solder Resistance Test	Test 260°C± 5°C for 10 ± 2 sec. Immerse body into solder 1/16" ± 1/32"	MIL-STD-750D METHOD-2031.2
2	Solderability Test	230°C ±5°C for 5 sec.	MIL-STD-750D METHOD-2026.1 0
3	Pull Test	1 kg in axial lead direction for 10 sec.	MIL-STD-750D METHOD-2036.4
4	Bend Test	0.5Kg Weight Applied To Each Lead, Bending Arcs 90 °C ± 5 °C For 3 Times	MIL-STD-750D METHOD-2036.4
5	High Temperature Reverse Bias Test	TA=100°C for 1000 Hours at VR=80% Rated VR	MIL-STD-750D METHOD-1038.4
6	Forward Operation Life Test	TA=25°C Rated Average Rectified Current	MIL-STD-750D METHOD-1027.3
7	Intermittent Operation Life Test	On state: 5 min with rated IRMS Power Off state: 5 min with Cool Forced Air. On and off for 1000 cycles.	MIL-STD-750D METHOD-1036.3
8	Pressure Cooker Test	15 PSIG, TA=121°C, 4 hours	MIL-S-19500 APPENOIXC
9	Temperature Cycling Test	-55°C~+125°C; 30 Minutes For Dwelled Time 5 minutes for transferred time. Total: 10 cycles.	MIL-STD-750D METHOD-1051.7
10	Thermal Shock Test	0°C for 5 minutes., 100°C for 5minutes, Total: 10 cycles	MIL-STD-750D METHOD-1056.7
11	Forward Surge Test	8.3ms Single Sale Sine-wave One Surge.	MIL-STD-750D METHOD-4066.4
12	Humidity Test	TA=65°C, RH=98% for 1000 hours.	MIL-STD-750D METHOD-1021.3
13	High Temperature Storage life Test	150°C for 1000 Hours	MIL-STD-750D METHOD-1031.5

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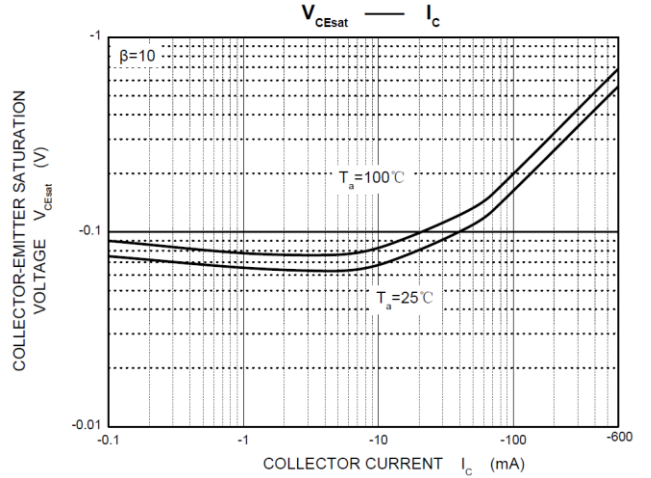
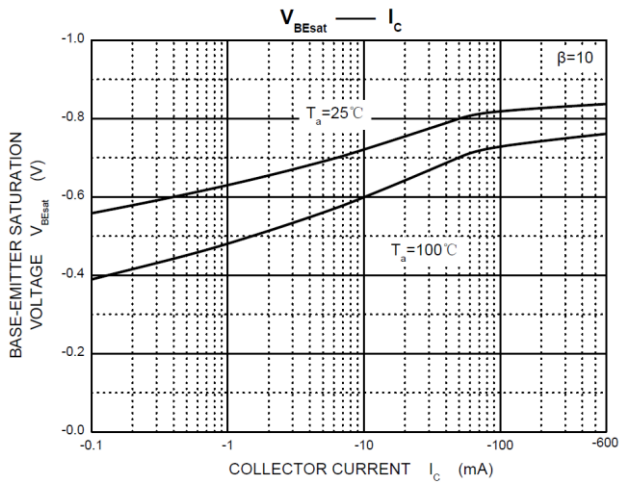
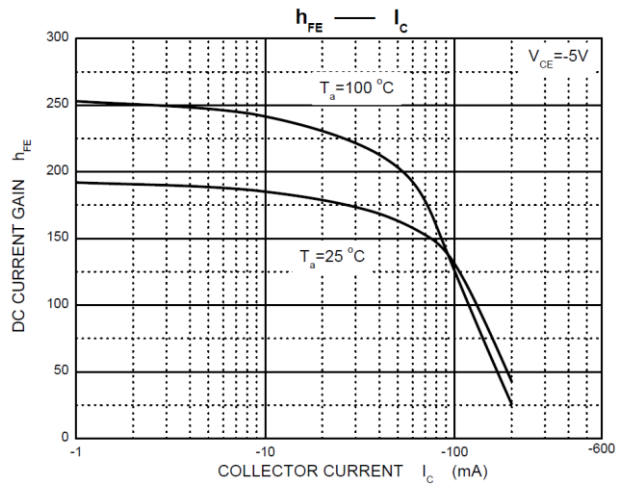
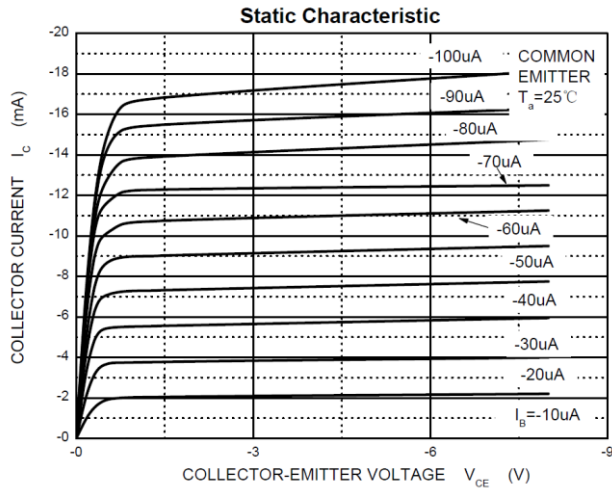
SUGGESTED REFLOW PROFILE (For Reference Only)



- Recommended peak temperature is over 245°C, If peak temperature is below 245 °C, you may adjust the following parameters; time length of peak temperature (longer), time length of soldering (longer), thickness of solder paste (thicker)
- Welding shall not exceed 2 times
- Remark: lead free solder paste (96.5 sn/3.0 Ag/0.5Cu)

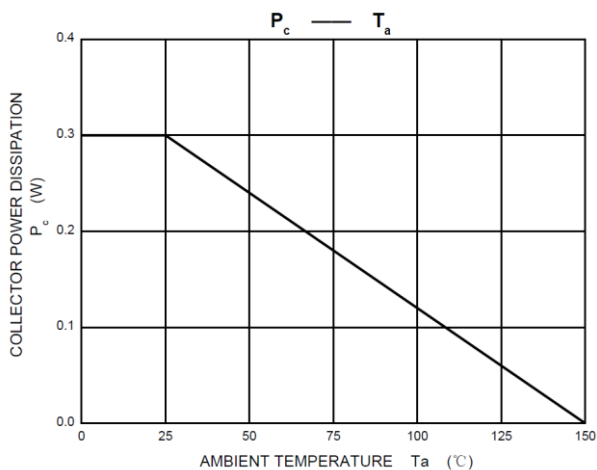
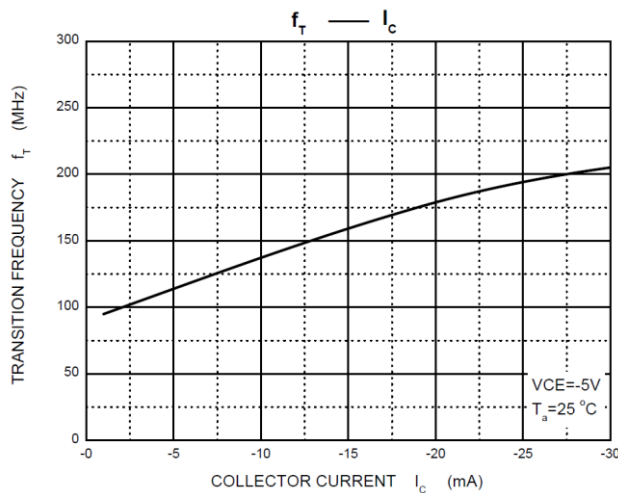
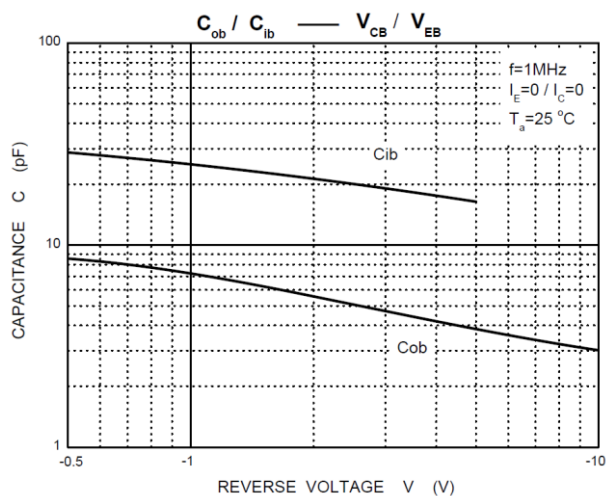
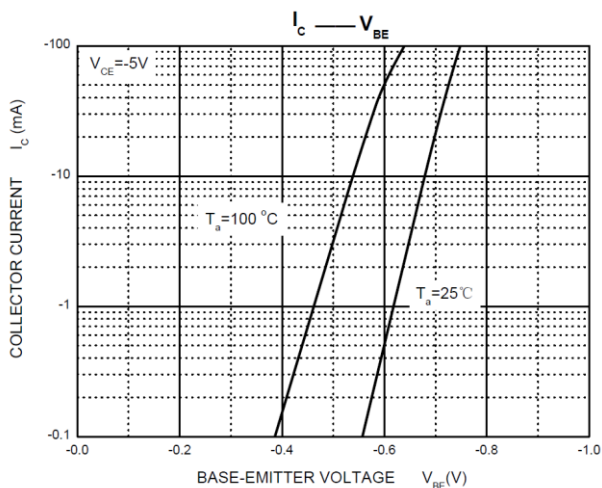
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RATINGS AND CHARACTERISTIC CURVES (For Reference Only)



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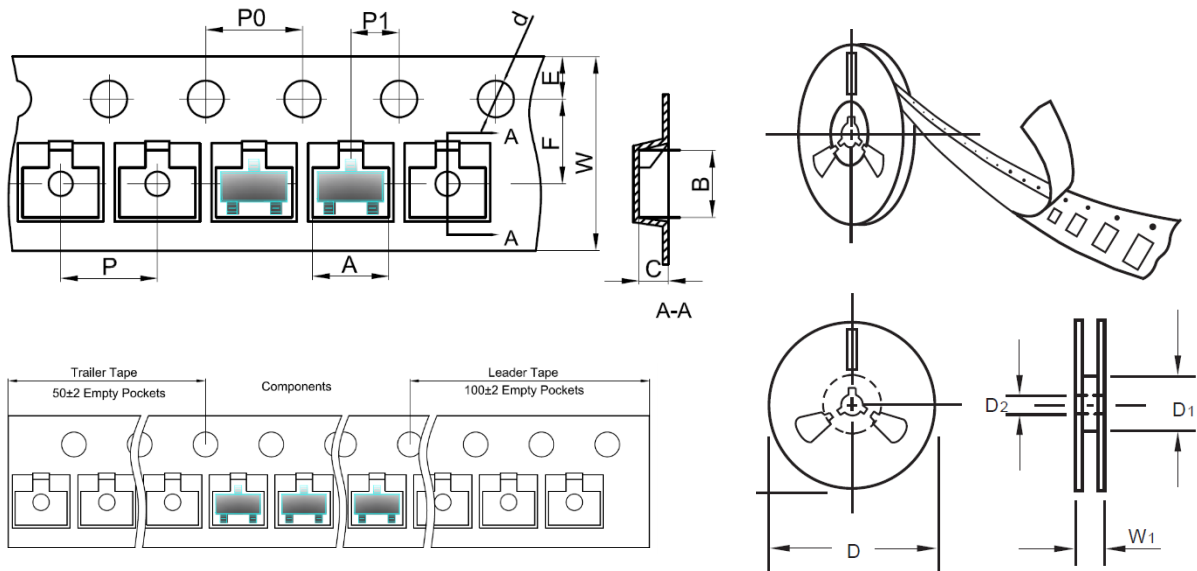
RATINGS AND CHARACTERISTIC CURVES (For Reference Only)



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TAPE/REEL (Unit: mm)

All Devices are packed in accordance with EIA standard RS-481-A and specifications.

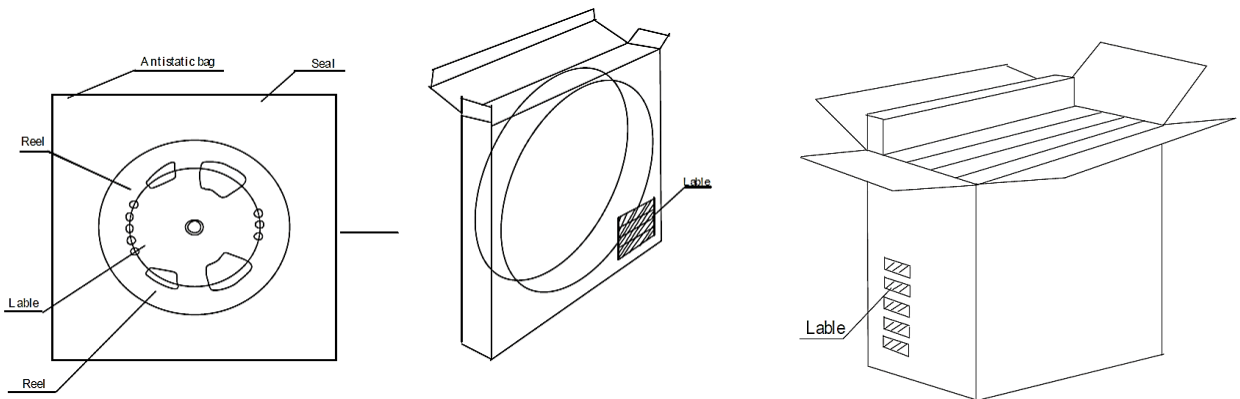


Item	Symbol	Tolerance	SOT-23
Carrier width	A	0.1	3.15
Carrier Length	B	0.1	2.77
Carrier Depth	C	0.1	1.22
Sprocket hole	d	0.05	1.55
7"Reel outside diameter	D	2.0	178.00
7"Reel inner diameter	D1	Min.	54.4
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	8.00
Reel width	W1	1.0	19.50

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PACKAGE

Case Code	Reel Size	MPQ (pcs)	Component Spacing (mm)	Qty. Per Box (pcs)	Inner Box L*W*H (mm)	Reel Size (mm)	Carton size L*W*H (mm)	Qty. Per Carton (pcs)	G. W (kg)
SOT-23	7"	3,000		45,000	212*207*207	178	430*430*230	180,000	6.5



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